Year II Milestones

8. Electronics Group
   (a) Construct and test 4-foot PC card with Varner and Ritt chips
   b) Construct clock distribution system for MTEST test-beam
   (c) Construct DAQ system for MTEST test-beam
   (d) Construct second-generation front-end card for MTEST test-beam
   (e) Submit second IBM-8RF chip (4-channel)

9. Integration Group
   (a) Integrate first-generation DAQ and 800 × 800 MCP with anode and front-end
   (b) Continue development of system test suite